

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Lu Yang Chen	11/30/2009
Yong Zheng	11/30/2009
Riguang Cheng	11/30/2009
Hua Zhang	11/30/2009

**RECEIVING PARTY DATA**

Name:	Cheng Uei Precision Industry Co., Ltd.
Street Address:	No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City
City:	Taipei Hsien
State/Country:	TAIWAN
Postal Code:	236

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	12628354

**CORRESPONDENCE DATA**

Fax Number: (949)743-8949  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
 Phone: 949-260-4797  
 Email: INFOCA@WPAT.COM  
 Correspondent Name: WPAT, PC INTELLECTUAL PROPERTY ATTORNEYS  
 Address Line 1: 2030 MAIN STREET, SUITE 1300  
 Address Line 4: IRVINE, CALIFORNIA 92614

ATTORNEY DOCKET NUMBER:	19908-009
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NAME OF SUBMITTER:	Anthony King
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Total Attachments: 2  
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OP \$40.00 12628354

**501028204**

**PATENT  
 REEL: 023584 FRAME: 0567**



**ASSIGNMENT BY INVENTOR(S) OF U.S. APPLICATION**

CU-A1079/US925

WHEREAS, I am the original, first and sole inventor and I own (if only one name is listed below) or an original, first and joint inventor and the joint inventors own (if plural names are listed below) (referred to as "ASSIGNOR" below) the subject matter which is claimed and for which a patent is sought on the invention (referred to as the "INVENTION" below) entitled:

Title: **SOLDERING APPARATUS AND SOLDERING METHOD**

the specification of which (check one):

- is executed on even date herewith.
- was filed on (day-month-year) as U.S. Application Number
- was filed on (day-month-year) as PCT Application Number
- was executed on the following date(s)

WHEREAS, **Cheng Uei Precision Industry Co., Ltd.**

having a postal address of **No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City, Taipei Hsien, 236, Taiwan, R.O.C.**

(referred to as "ASSIGNEE" below) desires to acquire the entire right, title and interest in and to the same in the U.S.;

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, ASSIGNOR, by these presents does sell, assign and transfer unto ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all patents granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent applications in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the INVENTION that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all patents referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Full Name of First or Sole Inventor Chen, Lu Yang	Post Office Address: No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City, Taipei Hsien, 236, Taiwan, R.O.C.
Citizenship China	Residence: No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City, Taipei Hsien, 236, Taiwan, R.O.C.
Date November 30, 2009	Signature <i>Lu Yang chen</i>

Full Name of Second of Joint Inventor Zheng, Yong	Post Office Address: No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City, Taipei Hsien, 236, Taiwan, R.O.C.
Citizenship China	Residence: No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City, Taipei Hsien, 236, Taiwan, R.O.C.
Date November 30, 2009	Signature <i>Yong zheng</i>

See following page(s) for additional joint inventors.

**SUPPLEMENTAL PAGE FOR AN ASSIGNMENT BY INVENTOR(S) OF U.S. APPLICATION**

Title: SOLDERING APPARATUS AND SOLDERING METHOD

Full Name of Joint Inventor Cheng, Riguang	Post Office Address: No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City, Taipei Hsien, 236, Taiwan, R.O.C.
Citizenship China	Residence: No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City, Taipei Hsien, 236, Taiwan, R.O.C.
Date November 30, 2009	Signature <i>Riguang Cheng</i>

Full Name of Joint Inventor Zhang, Hua	Post Office Address: No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City, Taipei Hsien, 236, Taiwan, R.O.C.
Citizenship China	Residence: No. 18, Chung Shan Rd., Tu-Cheng Industry Park, Tu-Cheng City, Taipei Hsien, 236, Taiwan, R.O.C.
Date November 30, 2009	Signature <i>Hua Zhang</i>

Full Name of Joint Inventor	Post Office Address
Citizenship	Residence
Date	Signature

Full Name of Joint Inventor	Post Office Address
Citizenship	Residence
Date	Signature

See following page(s) for additional joint inventors.